

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

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T-1 3/4 (5mm) BI-LEVEL LED INDICATOR

Part Number: WP1503EB/2YD Yellow

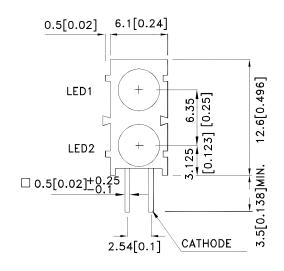
Features

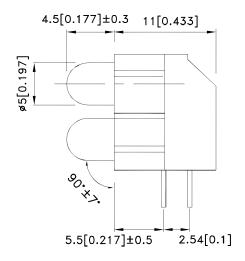
- Pre-trimmed leads for pc board mounting.
- Stackable units.
- Colors can be mixed in a single housing.
- Black case enhances contrast ratio.
- Wide viewing angle.
- High reliability life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

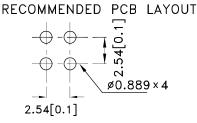
Description

The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode.

Package Dimensions









- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.
 4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

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Selection Guide

Part No.	Dice	Iv (mcd) [2] Dice Lens Type @ 10mA		,	Viewing Angle [1]
			Min.	Тур.	201/2
WP1503EB/2YD	Yellow (GaAsP/GaP)	Yellow Diffused	15	30	60°

Notes:

- θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 Luminous intensity/ luminous Flux: +/-15%.
 Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Yellow	590		nm	IF=20mA
λD [1]	Dominant Wavelength	Yellow	588		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Yellow	35		nm	IF=20mA
С	Capacitance	Yellow	20		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Yellow	2.1	2.5	V	IF=20mA
lr	Reverse Current	Yellow		10	uA	VR = 5V

Notes:

- Wavelength: +/-1nm.
 Forward Voltage: +/-0.1V.
- 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.
- 4. Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or

Absolute Maximum Ratings at TA=25°C

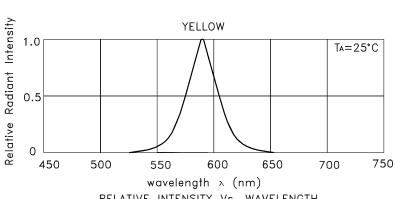
Parameter	Yellow	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	140	mA	
Reverse Voltage	5	V	
Operating/Storage Temperature	-40°C To +85°C		
Lead Solder Temperature [2]	260°C For 3 Seconds		
Lead Solder Temperature [3]	260°C For 5 Seconds		

Notes:

- 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
 2. 2mm below package base.
 3. 5mm below package base.

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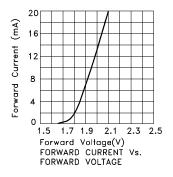
Kingbright

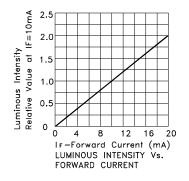


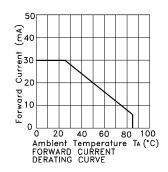
RELATIVE INTENSITY Vs. WAVELENGTH

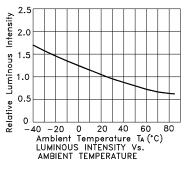
Yellow

WP1503EB/2YD



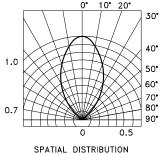






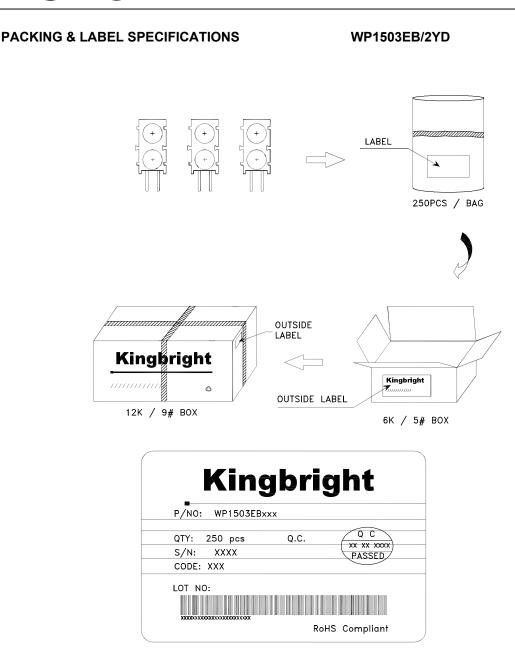
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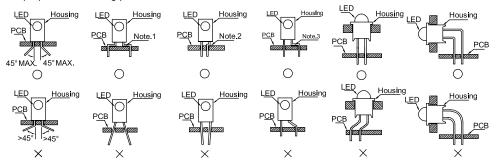
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Kingbright

PRECAUTIONS

- 1. Storage conditions:
 - a. Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.
 - b.LEDs should be stored with temperature ≤30°C and relative humidity < 60%.
 - c.Product in the original sealed package is recommended to be assembled within 72 hours of opening.

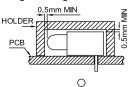
 Product in opened package for more than a week should be baked for 30 (+10/-0) hours at $85 \sim 100^{\circ}$ C.
- 2. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

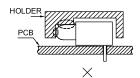


" \bigcirc " Correct mounting method " imes " Incorrect mounting method

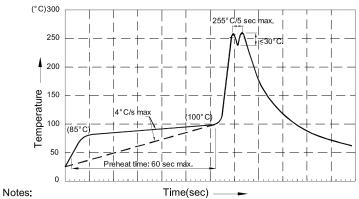
Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.





- 4. The tip of the soldering iron should never touch the lens epoxy.
- 5. Through-hole LEDs are incompatible with reflow soldering.
- If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- 7. Recommended Wave Soldering Profiles:



- 1.Recommend pre-heat temperature of 105° C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260° C
- 2.Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
- 3.Do not apply stress to the epoxy resin while the temperature is above 85°C.
- 4. Fixtures should not incur stress on the component when mounting and during soldering process.
- 5.SAC 305 solder alloy is recommended.
- 6.No more than one wave soldering pass.

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